

Amendments to the Claims:

Please cancel claims 1, 7, 8, 13 - 19, 25 and 27 without prejudice or disclaimer of the subject matter thereof, amend claims 10 and 26 and add the following new claims.

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (canceled)

Claims 2 - 6 (canceled)

Claims 7 - 8 (Canceled)

Claim 9 (canceled)

10. (currently amended) A vacuum processing apparatus comprising:

two vacuum processing chambers disposed adjacent one another, each of the two vacuum processing chambers ~~being configured with a top, bottom and side wall portions which are separate from the adjacent vacuum processing chamber and~~ being respectively detachably connected to the vacuum processing apparatus, the two adjacent vacuum processing chambers being supplied with a processing gas to generate plasma utilized for processing a wafer disposed therein; and

plural controllers which control the supply of the processing gas directly into each of the two adjacent vacuum processing chambers so as to enable processing

of the wafer disposed therein, the plural controllers being disposed between the side wall portions of the two adjacent vacuum processing chambers;

wherein the plural controllers are disposed adjacent one another in a vertical direction, one of the plural controllers directly supplying gas to one of the two adjacent vacuum processing chambers and the other of the plural controllers directly supplying gas to the other of the two adjacent vacuum processing chambers, and the plural controllers are detachable from the vacuum processing apparatus as one unit.

11. (previously presented) A vacuum processing apparatus according to claim 10, further comprising a transfer unit enabling transfer of the wafer, wherein each of the two adjacent vacuum processing chambers is detachably connected on one respective side wall portion thereof to the transfer unit so as to enable transfer of the wafer between a respective vacuum processing chamber and the transfer unit.

12. (previously presented) A vacuum processing chamber according to claim 11, wherein the transfer unit has a polygonal shape in plan view, and each of the two adjacent vacuum processing chambers are disposed on respective side walls forming two adjacent sides of the polygonal shape of the transfer unit.

Claims 13 - 19 (canceled)

20. (previously presented) A vacuum processing apparatus according to claim 12, wherein the plural controllers are disposed in a space between the two adjacent vacuum processing chambers.

Claims 21 - 24 (canceled)

Claim 25 (canceled)

26. (currently amended) A vacuum processing apparatus according to claim ~~10~~ 11, wherein each of the two adjacent vacuum processing chambers is detachably connected on another side wall portion thereof to the one of the plural controllers.

Claim 27 (canceled)

28. (previously presented) A vacuum processing apparatus according to claim 11, wherein the transfer unit further enables transfer of the object to be processed between an atmospheric unit which holds the object to be processed outside of the transfer unit and at least one of to and from at least one of the two adjacent vacuum processing chambers through the transfer unit.

29. (new) A vacuum processing apparatus according to claim 10, wherein each of the two vacuum processing chambers are configured with a top, bottom and side wall portions which are separate from the adjacent vacuum processing chamber.

30. (new) A vacuum processing apparatus according to claim 10, wherein the plural controllers are disposed in a space between the two adjacent vacuum processing chambers.

31. (new) A vacuum processing apparatus according to claim 10, wherein the plural controllers are mass flow controlling devices.

32. (new) A vacuum processing apparatus comprising:

a transfer unit in which a wafer is transferred;

plural processing chambers detachably connected to a periphery of a side wall portion of the transfer unit; and

a mass flow controlling unit including two mass flow controlling devices which respectively control feeding of gas to respective processing chambers;

wherein the mass flow control unit is disposed between two processing chambers so that the two processing chambers are disposed in a space opposite to portions of sides of the mass flow controlling unit; and

wherein the two mass flow controlling devices are disposed adjacent one another in a vertical direction and are detachable from the two processing chambers as one unit.

33. (new) A vacuum processing apparatus comprising:

two vacuum processing chambers disposed adjacent one another, each of the two vacuum processing chambers being separate from the adjacent vacuum processing chamber and being respectively detachably connected to the vacuum processing apparatus, the two adjacent vacuum processing chambers being supplied with a processing gas to generate plasma utilized for processing a wafer disposed therein; and

plural controllers which control the supply of the processing gas directly into each of the adjacent vacuum processing chambers so as to enable processing of the

wafer disposed therein, the plural controllers being disposed between side wall portions of the two adjacent vacuum processing chambers;

wherein the plural controllers are disposed adjacent one another in a vertical direction, one of the plural controllers directly supplying gas to one of the two adjacent vacuum processing chambers and the other of the plural controllers directly supplying gas to the other of the two adjacent vacuum processing chambers, the plural controllers being detachable from the vacuum processing apparatus as one unit.

34. (new) A vacuum processing apparatus according to claim 33, further comprising a transfer unit enabling transfer of the wafer, wherein each of the adjacent vacuum processing chambers is detachably connected to the transfer unit so as to enable transfer of the wafer between a respective vacuum processing chamber and the transfer unit, the plural controllers being disposed in a space between the adjacent vacuum processing chambers.